EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	400469	(center middle) with (pad paddle bond bonding electrode terminal contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:51
L2	70146	(memory chip die dice multichip semiconductor ic (integrated adj circuit) component) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:52
L3	40923	(first second upper lower multi multiple plurality) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:53
L4	8648	(package packaging packaged module apparatus) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:53
L5	2758	4 and ((exposing exposed expose opening) with (bondpad bond pad paddle electrode contact))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:55
L6	2269	5 and (metal pattern rearrange$6 redistribut$5 wiring wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 18:22
L7	2110	(edge perimeter border end peripheral$3) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 17:59
L8	1621	(insulating insulat$6 resin epoxy encapsulat$3 encase) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 18:23

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L9	2257	5 and (metal pattern rearrange$6 redistribut$5 trace iring wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB.	OR	ON	2006/03/16 18:22
L10	1735	(insulating insulat$6 resin epoxy encapsulat$3 encase) and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 18:39
L11	2	"6642627".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/16 18:39
L12	1	"4984050".PN.	USPAT; USOCR	OR	OFF	2006/03/16 19:35
L13	1	"5723822".PN.	USPAT; USOCR	OR	OFF	2006/03/16 19:35
L14	1	"5751065".PN.	USPAT; USOCR	OR	OFF	2006/03/16 19:35
L15	1	"6111317".PN.	USPAT; USOCR	OR	OFF	2006/03/16 19:35
L16	1	"6111317".PN.	USPAT; USOCR	OR	OFF	2006/03/16 19:36